

Notice of References Cited

Application/Control No.

09/916,491

Applicant(s)/Patent Under

Reexamination

GERRITS ET AL.

Examiner

D. I. Lee

Art Unit

2876

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U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,736,646 A1	04-1998	Dickinson et al.	73/814
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Keizou Sakurai, Electronic Manufacturing Technology Symposium, 1995, [The basic processing parameters and reliability evaluation results for the new IC-Card packaging method by using transfer molding]
	V	Ed Marsh, IEEE Technical Applications Conference and Workshops Northcon95, Oct. 1995 [Packaging Guidelines for PC Cards]
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.